

### Abstract of the Invention

A light emitting assembly includes a metal substrate for dissipating heat from the assembly. The metal substrate includes an electrically insulating layer or coating on at least one side.

5 Circuit traces are applied to the electrically insulating layer using either thick or thin film techniques. At least the ends of the circuit traces include a metallic section to which leads of light emitting elements are soldered or wire-bonded. A metallic section is provided adjacent the light emitting element to transfer  
10 heat to the underlying substrate and/or to reflect light from the element away from the substrate. A clear finish retards tarnishing of the reflecting metallic section.